[Translation]
NOTICE: The following report is an English Translation of the Japanese-language original.
This press release is made pursuant to the requirements under the listing rules of, and reported to, the Tokyo Stock Exchange.

March 3, 2015

To whom it may concern,

Company name: SUMCO Corporation
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(Code: 3436, TSE First Section)
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Announcement regarding Change in the Use of Proceeds from the Issuance of Class Stock by Third-Party Allotment

The Company hereby announces that it has decided to change the use of proceeds procured by the issuance of class stock as disclosed on the "Notice on Issuance of Shares by Third-Party Allotment" dated March 8, 2012.

1. Reason and Substance of Modification

The Company has resolved, at the board of directors meeting held today, its "New Medium-Term Management Strategy", which is a strategic roadmap for the new growth stage following the Business Reorganization Plan, and its "Capital Increase and Restructuring Plan" (the "Plan") which focuses on the strengthening of the Company's financial base and raising funds for growth through the issuance of common stock of the Company and acquisition of class stock of the Company as announced on its press release "Announcement regarding: Shelf Registration for the Issuance of New Shares and Schedule of Secondary Offering; Reduction in the Amount of Capital Reserve and Reduction in the Amount of Capital Stock and Capital Reserve Concurrently with the Issuance of New Shares; and Acquisition of Treasury Stock (Class B Stock) (Acquisition of Treasury Stock Pursuant to Article 156 of the Companies Act)" dated March 3, 2015.

Additionally, the Company has executed, as of today, the "Memorandum of Understanding Concerning the Treatment of Class Stock" (the "MOU") with Nippon Steel & Sumitomo Metal Corporation, Mitsubishi Materials Corporation and Japan Industrial Solutions Investment Limited Partnership I (together, the "Three Class A Shareholders"), who are the holders of the Class A Stock of the Company. In accordance with the MOU, the Company intends to conduct procedures (i) to acquire and cancel its issue of Class A Stock and (ii) to repurchase and cancel the Class B Stock to be delivered to the Three Class A Shareholders upon the exercise of the put

options attached to Class A Stock, the consideration for which is a cash payment and Class B Stock, by the Three Class A Shareholders.

With respect to the proceeds from the issuance of class stock of approximately 44,700 million yen, the condition of appropriation as of January 31, 2015, the scheduled timing of disbursement, was as follows. Pursuant to the Business Reorganization Plan which commenced in fiscal year 2012, the Company group steadily implemented various measures such as its withdrawal from the solar wafer business, a restructuring and consolidation of the semiconductor silicon wafer manufacturing facilities and a review of workforce allocation in relation to the restructuring of its manufacturing system, and endeavored to reduce fixed costs and enhance profitability. However, since the formulation of the Business Reorganization Plan, the business environment continued to fall below the level anticipated at the time of the formulation of the Business Reorganization Plan. Because of this, the Company placed a priority on maintaining its financial stability and reduced its capital expenditures, research and development investments and other items it deemed not immediately necessary and, as a result, 13,832 million yen remain undisbursed. Since the use of proceeds of the undisbursed funds has been under review along with the Plan, the Company determined, as of today, the date on which the Plan was resolved, to appropriate the undisbursed funds to a portion of the cash payment to be delivered on May 11, 2015 when the Three Class A Shareholders exercise their put options, the consideration for which is a cash payment and Class B Stock.

[Before Change]

(million yen)

Specific Purpose		Planned Amount of Disbursement	Scheduled Timing of Disbursement
(i)	Investment to respond to increasing precision in silicon wafers for semiconductors and investment into research and development aimed at increasing competitiveness further, etc.	14,100	June 2012 ~ Jan 2015
(ii)	Capital expenditure pertaining to maintaining and renewing business assets (wafer manufacturing equipment, etc.)	19,100	June 2012 ~ Jan 2015
(iii)	Operating funds for business activities	11,500	June 2012 ~ Jan 2015
	Total	44,700	

* Funds procured will be managed in a bank account until they are to be disbursed.

[After Change]

(million yen)

Specific Purpose		Amount Appropriated	Scheduled Timing of Disbursement
(i)	Investment to respond to increasing precision in silicon wafers for semiconductors and investment into research and development aimed at increasing competitiveness further, etc.	11,438	June 2012 ~ Jan 2015
(ii)	Capital expenditure pertaining to maintaining and renewing business assets (wafer manufacturing equipment, etc.)	7,930	June 2012 ~ Jan 2015
(iii)	Operating funds for business activities	11,500	June 2012 ~ Jan 2015
(iv)	A portion of cash payment to be delivered upon the exercise of the put options attached to Class A Stock	13,832 (Scheduled)	May 2015 (Scheduled)
	Total	44,700	

* Funds procured will be managed in a bank account until they are to be disbursed.

(Note) The amount appropriated is an actual result as of January 31, 2015.

2. Impact on Financial Results

The Company expects insignificant impact on its financial results and its consolidated financial results. Please refer to the "Brief Statement of Consolidated Financial Results Fiscal Year 2014" released on February 12, 2015 with respect to the consolidated business forecasts for the first quarter of the fiscal year ending December 31, 2015.

End of document

Note: This material is prepared for the purpose of continuous disclosure to general shareholders and investors the change in the use of proceeds from the issuance of class stock by third-party allotment, and does not constitute an offer or solicitation of securities in any state or jurisdiction including Japan. Estimates, expectations, forecasts, and other future information set out in this notice have been prepared based on the information that is available for the Company as of today and on certain assumptions and qualifications, and the actual financial performance or result might be substantially different from such future information contained in the material due to risk factors including domestic and global economic conditions, trends of semiconductor markets, and foreign exchanges.

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